

Title (en)
METHOD FOR APPLYING A SUBSTRATE

Title (de)
VERFAHREN ZUM AUFBRINGEN EINES SUBSTRATS

Title (fr)
PROCEDE POUR L'APPLICATION D'UN SUBSTRAT

Publication
EP 1332516 A1 20030806 (DE)

Application
EP 01988946 A 20011015

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Abstract (en)
[origin: DE10052293A1] A substrate (4) fits with a gap and is curved in relation to a protective layer (5). As it is laid on, the substrate exerts almost constant pressure on the protective layer. Air or liquid is applied as pressure to the substrate's side turned away from the protective layer. Controlling the pressure of the air or liquid in the hollow space between the substrate and a carrier body (2) causes the substrate to arch and be released from the carrier body.

IPC 1-7
H01L 21/302; H01L 21/68

IPC 8 full level
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Citation (search report)
See references of WO 0235591A1

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